

BOARD CHARACTERISTICS


Copper Layer Count:	2	Board Thickness:	62.00 mils
Board overall dimensions:	3550.00 mils x 3982.07 mils	Min hole diameter:	8.00 mils
Min track/spacing:	8.00 mils / 8.00 mils	Impedance Control:	No
Copper Finish:	ENIG	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	Yes, Bevelled		

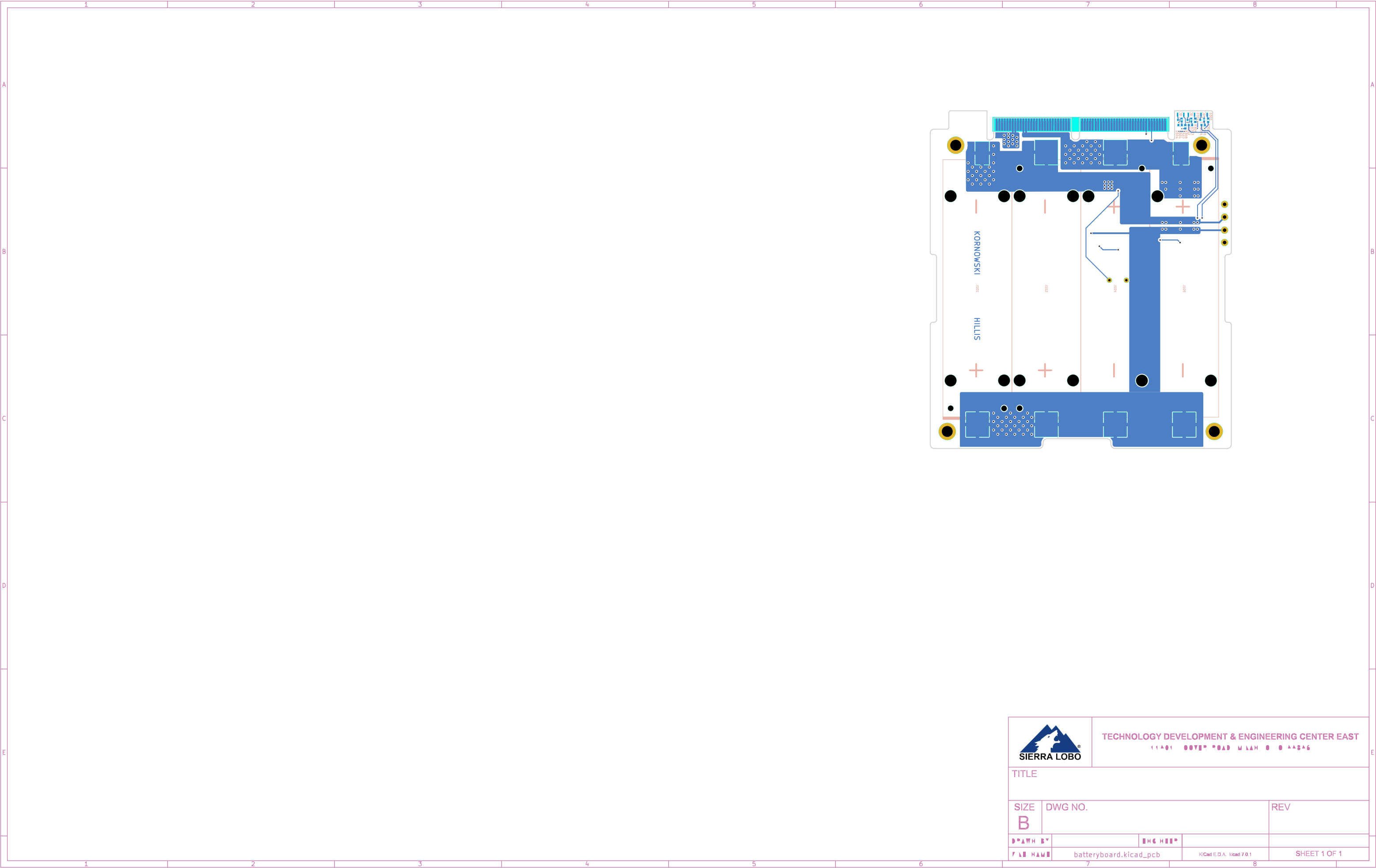
FAB NOTES:


1. IPC-6012E Class 2
2. Green soldermask, White silkscreen.
3. Fabricate on Nelco N7000-2HT
4. 2oz outer copper.
5. Bevel edge connector 30 degrees minimum.
7. Board target thickness shall be 0.062"
8. Gold finger plating thickness shall be 1"U

ASSEMBLY NOTES:

1. J-STD-001G Class 2
2. BOM provided with submitted files shall be the controlling document for component information.
3. Do not apply solder to pads of DNP components
4. Stake components specified in BOM with 3M 2216
5. Conformal Coat with Arathane 5750:  
Ensure coating does not prevent electrical contact with connectors and mounting holes.

		TECHNOLOGY DEVELOPMENT & ENGINEERING CENTER EAST 11401 BOYER ROAD MARIETTA, GA 30066	
TITLE			
SIZE B	DWG NO.		REV
DRAWN BY TAM HAWK	CHKD BY	KICad E.D.A. Kicad 7.0.1	SHEET 1 OF 1
batteryboard.kicad_pcb			
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 SIERRA LOBO®		TECHNOLOGY DEVELOPMENT & ENGINEERING CENTER EAST 11401 BOYD ROAD MANKATO, MN 56001	
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